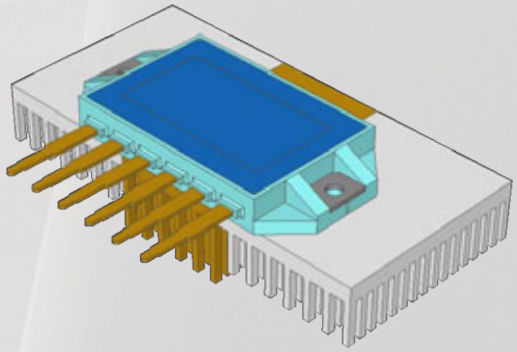
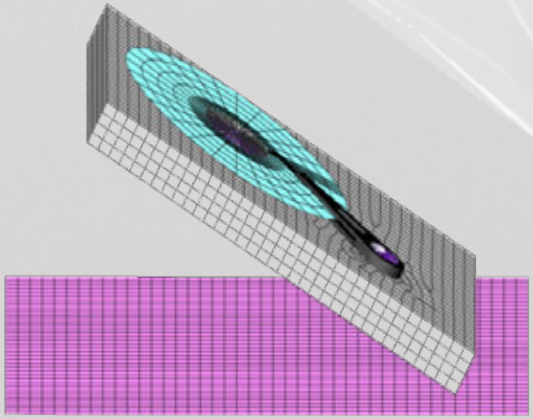
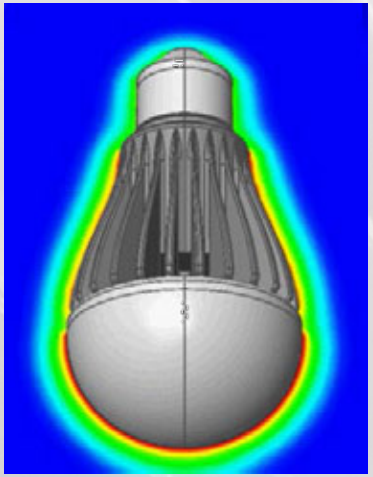
產品設計導向分析軟體

電子零組件實例





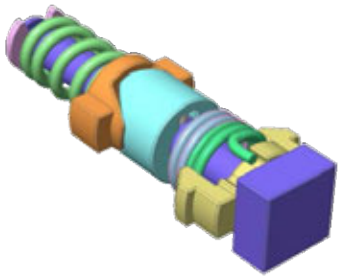


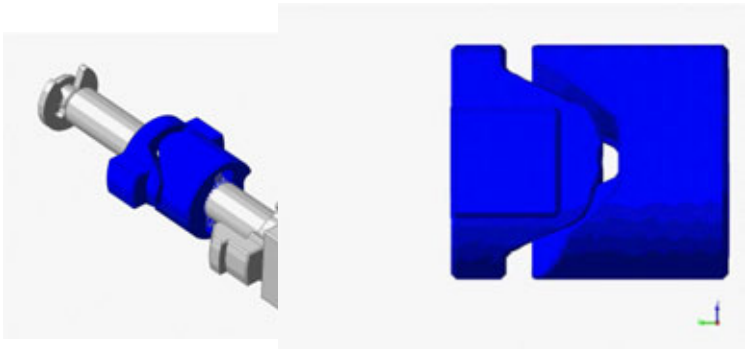
midas NFX

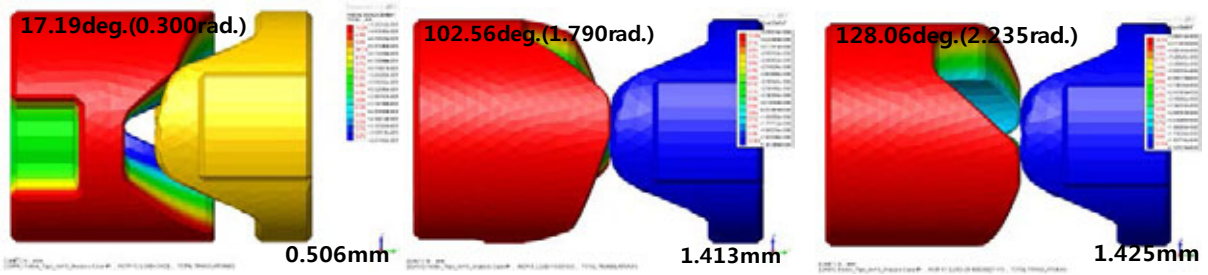
凸輪彈簧耐久性分析

midas NFX

一分析模型



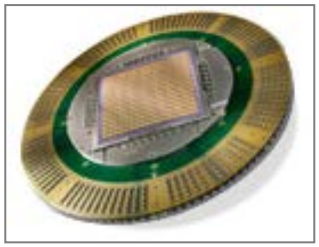


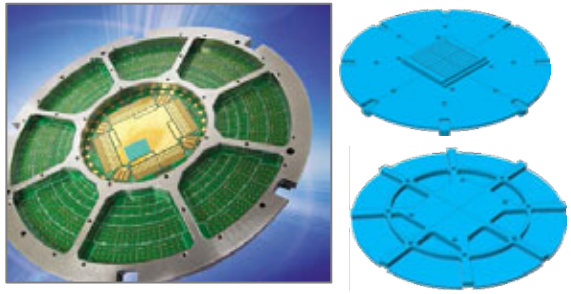


晶圓探針卡熱應力分析

midas NFX

分析模型

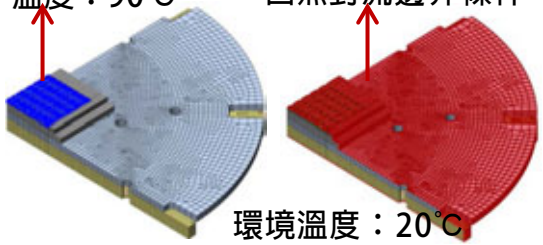




分析條件

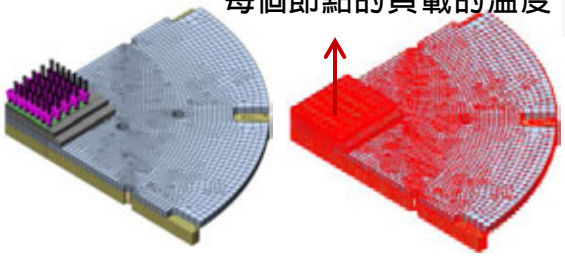
溫度：90℃

自然對流邊界條件

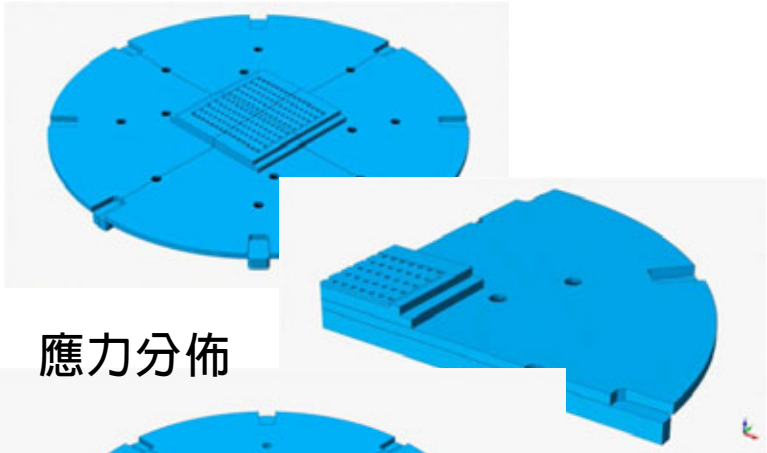


環境溫度：20℃

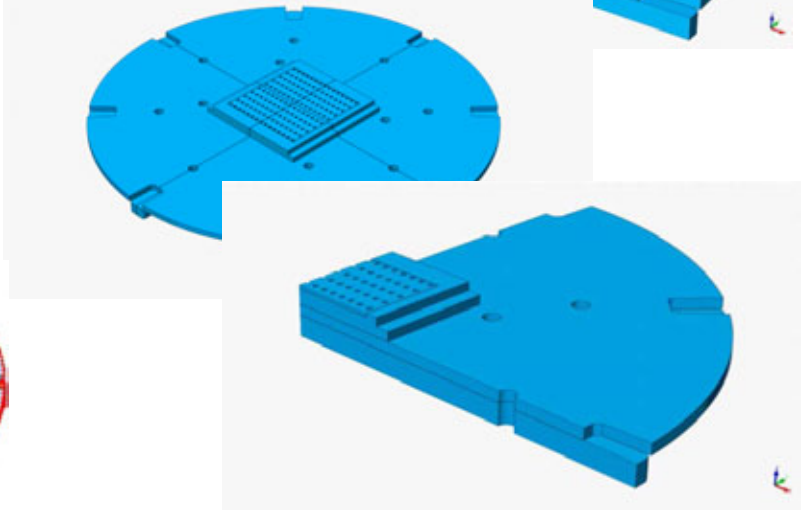
每個節點的負載的溫度



溫度分佈



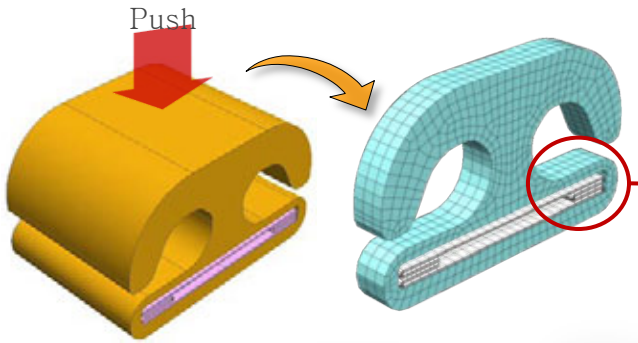
應力分佈



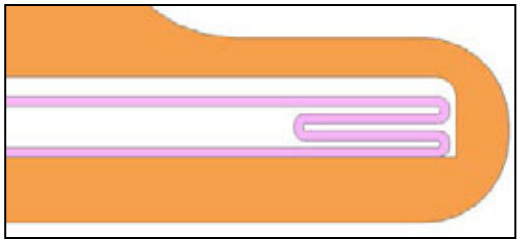
自動門傳感器接觸分析

midas NFX

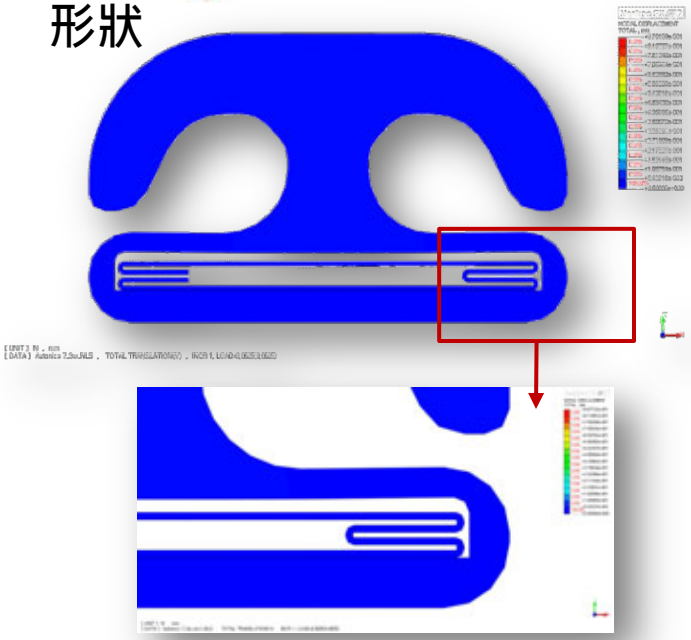
分析模型



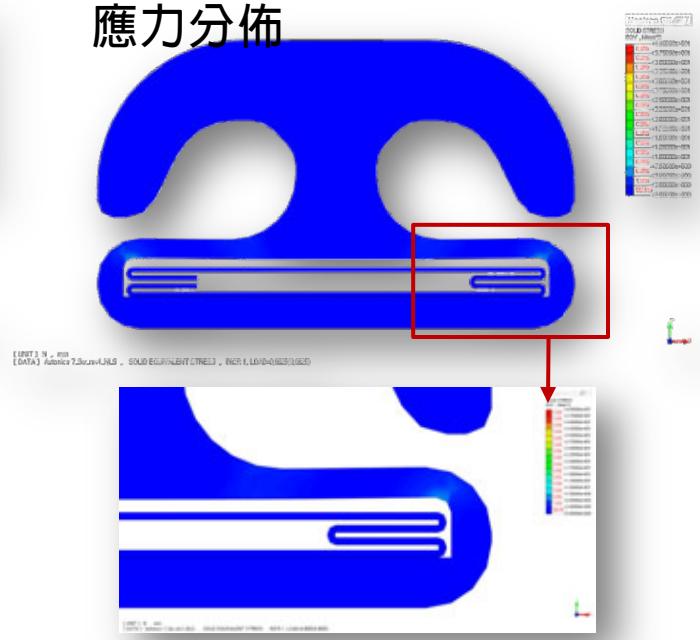
自動門安全傳感器組件



形狀



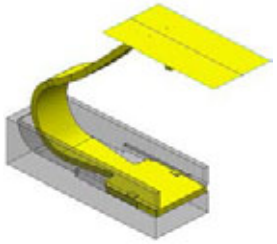
應力分佈

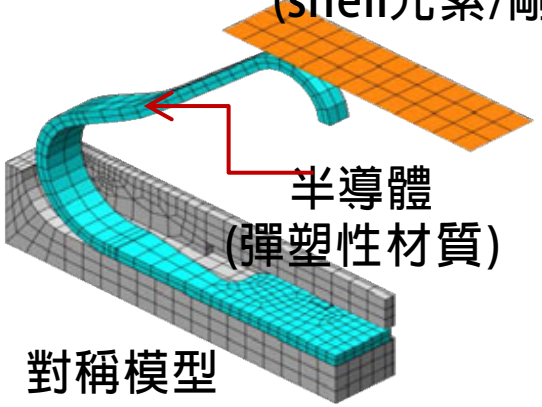


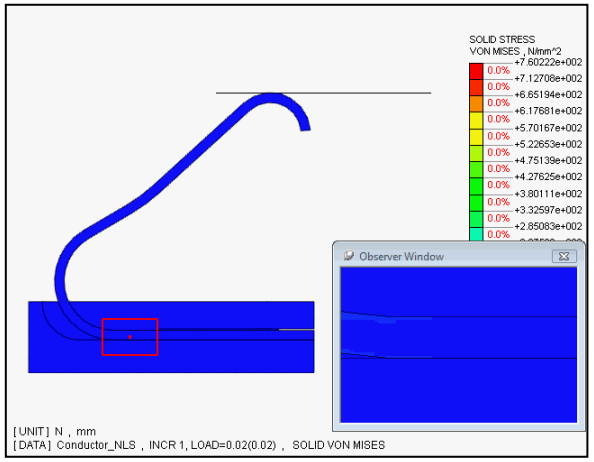
半導體彈片分析

midas NFX

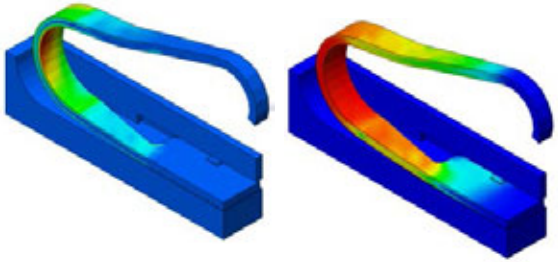
一分析模型





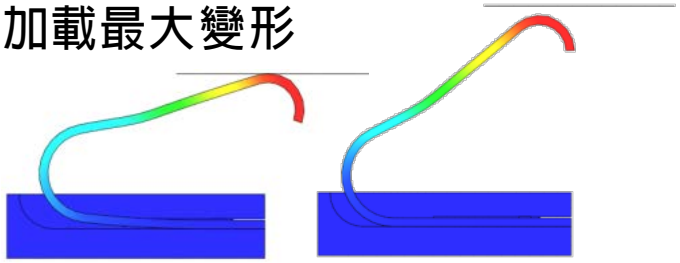


應力和永久變形



非線性應力　　塑性應變

加載最大變形

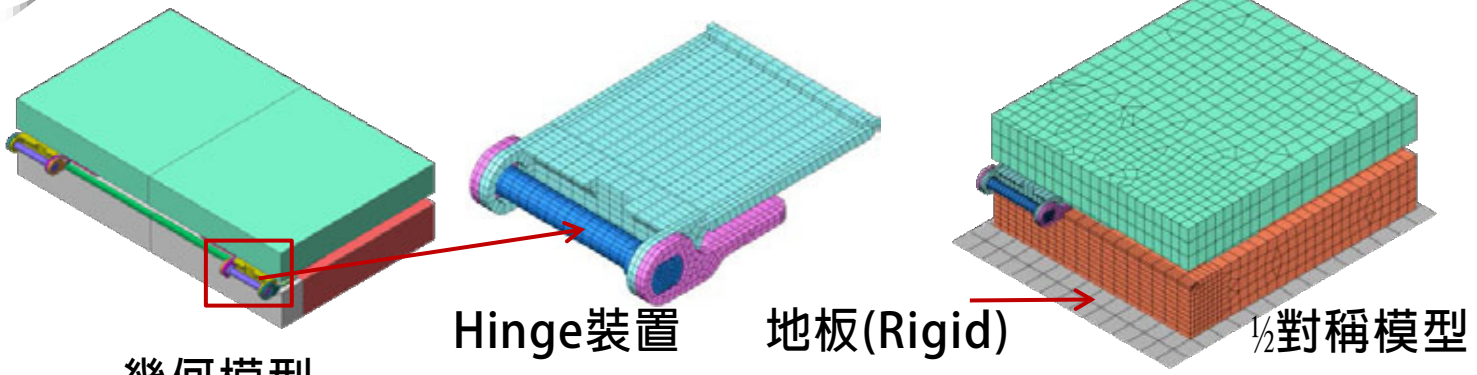


卸載後變形

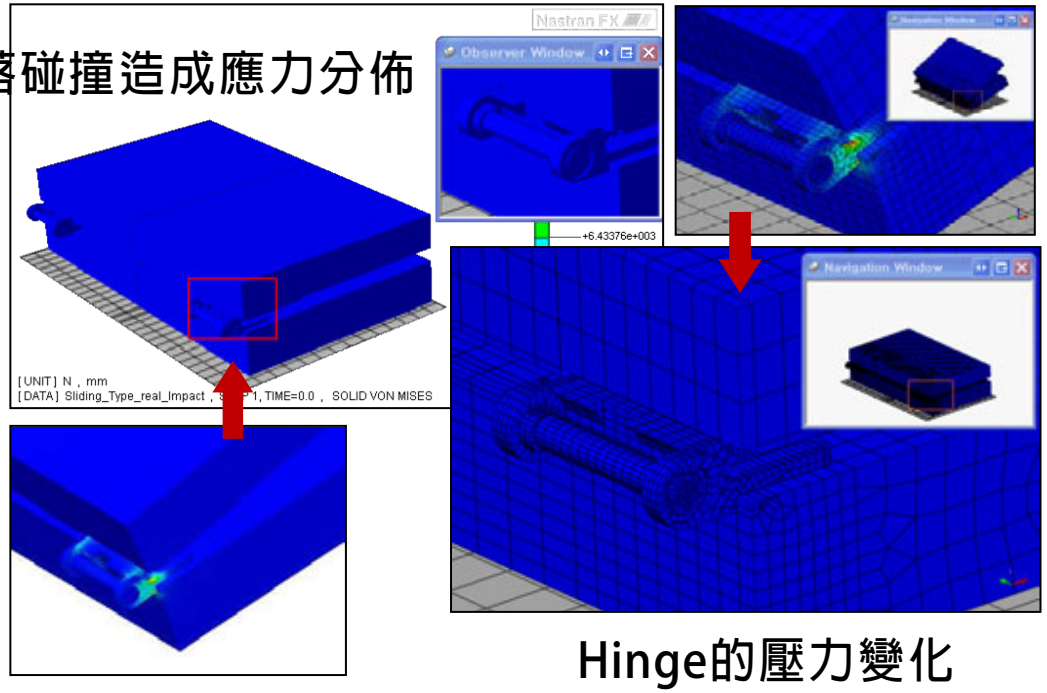
手機hinge強度分析

midas NFX

一分析模型



掉落碰撞造成應力分佈



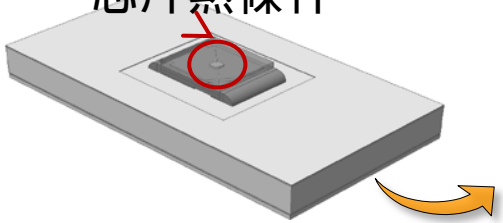
Hinge的壓力變化

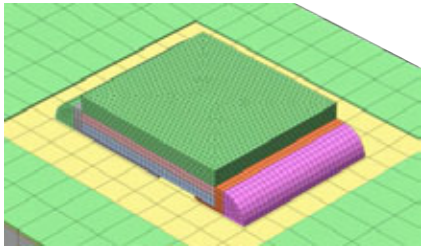
背光單元的熱傳分析

midas NFX

分析模型

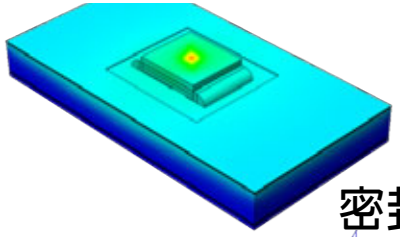
芯片熱條件

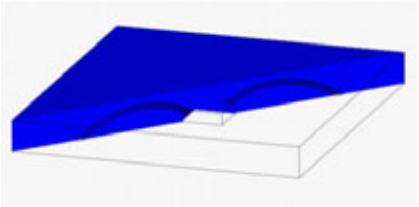




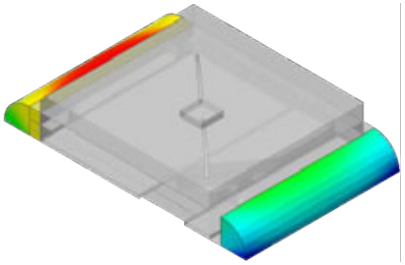
六面體/四面體混合網格

溫度分佈

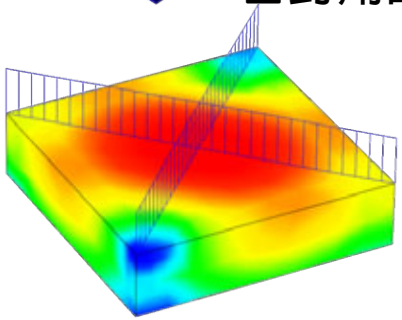




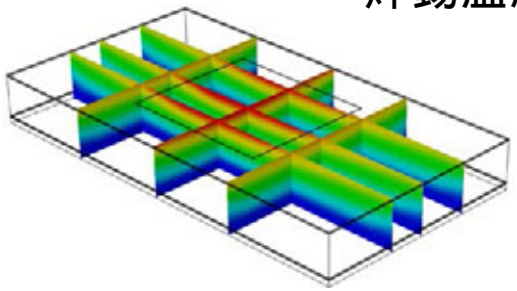
密封劑的溫度分佈的變化



焊錫溫度分佈



溫度分佈

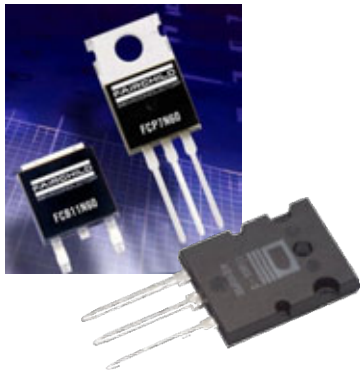


部分層的溫度分佈

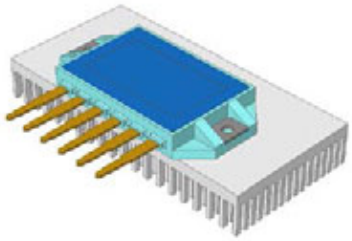
散熱器設計

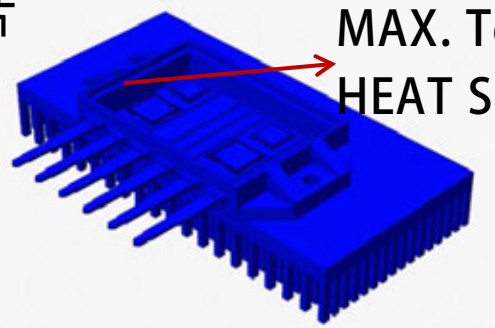
midas NFX

分析模型



瞬態熱傳分析設計散熱片





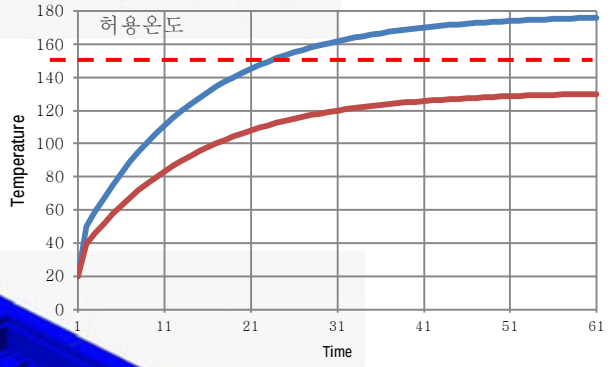
MAX. Temp : 176℃

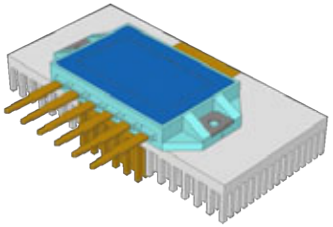
HEAT SINK需要重新設計

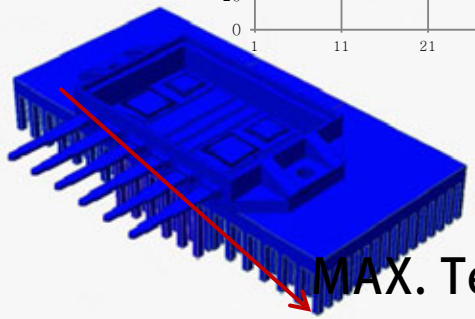
傳導和對流，提高性能

散熱面積：15%

變更材料：鋁+銅







MAX. Temp : 132℃

HEAT SINK滿足設計標準